

IEEE World Haptics Conference, Tokyo, JAPAN, July 9 - 12

Program (version 2.0)

Day 1: Tuesday, July 9th, 2019						Day 2: Wednesday, July 10th, 2019					Day 3: Thursday, July 11th, 2019					Day 4: Friday, July 12th, 2019					
Hall N		Hall S		2F Lounge	2F Terrace	1F Room A-D	2F Main Hall		2F Lounge	2F Terrace	1F Room A-C	2F Main Hall		2F Lounge	2F Terrace	1F Room A-C	2F Main Hall		2F Lounge	2F Terrace	1F Room A-C
8:30 - Registration						8:30 - Registration					8:30 - Registration					8:30 - Registration					
9:00 - 10:30 Workshop 4		Workshop 1				Workshops 2, 3, 5	9:20 - 10:00 Award nominated paper session 1		Exhibitions setup (Design showcase & Industrial exhibitions)		Demos 1, WIP poster 1, and SIC setup	9:00 - 10:00 Award nominated paper session 2				Demos 1 and WIP poster 1 move-out	9:00 - 10:00 Award nominated paper session 3				All Demos, WIP, and SIC move-out
10:30 - 11:00 Coffee break				Coffee break	10:00 - 11:00 Oral session 1A		10:00 - 11:00 Oral session 2A					10:00 - 11:00 Oral session 3A									
11:00 - 12:30 Workshop 4		Workshop 1		Workshops 2, 3, 5	11:00 - 11:30 Coffee break		11:00 - 11:30 Coffee break					11:00 - 11:30 Coffee break									
11:30 - 12:30 Oral session 1B					11:30 - 12:30 Oral session 2B		11:30 - 12:30 Oral session 3B														
12:30 - 14:00 Lunch break						12:30 - 14:00 Lunch break / Interactive sessions setup / SIC Mobility presentation					12:30 - 14:00 Lunch break / Interactive sessions setup					12:30 - 14:00 Lunch break / Interactive sessions setup					
14:00 - 14:15 Opening						14:00 - 16:00 Interactive session 1 14:00-15:00 core time of 1A 15:00-16:00 core time of 1B					Industrial exhibitions		Demos 2 and WIP poster 2 setup	14:00 - 16:00 Interactive session 2 14:00-15:00 core time of 2A 15:00-16:00 core time of 2B		Industrial exhibitions		Exhibitions move-out	1F area withdrawal		
14:15 - 17:15 CCC		Exhibitions setup (Design showcase & Industrial exhibitions)			16:00 - 16:30 Teaser session 1		Design showcase & Industrial exhibitions		Demos 1 WIP poster 1 SIC	16:00 - 16:30 Teaser session 2		WIP interactive session		Design showcase & Industrial exhibitions		Demos 2 WIP poster 2 SIC					
17:15 - 18:00 Self (subway) transportation to Univ. Tokyo						18:00 - 18:30 Reception hall open / ToH booth setup					18:00 - 19:00 Self (train) transportation to banquet					17:15 - 18:00 Closing					
18:00 - 20:00 Technical tour @ University of Tokyo *pre-registration required						18:30 - 20:30 Reception @2F with ToH interactive session & Industrial Exhibitions					19:00 - 21:30 Banquet @ MeijjiKincken					18:00 - 21:00 All area withdrawal					
						20:30 - 21:00 Closing the reception															